**< DE/EJ/ET/EN/EX/EQ/IE/IS/IC >: < 22636> : < Emerging Trends in Electronics >:**

**< Recent Electronic Components >: <UO2c.2: Describe the concept of reflow soldering method**.**>**

**<Assessments>: <Formative>**

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| **Set 1: Question No. 1** | **Set 1: Question No. 2** | **Set 1: Question No. 3** |
| 1. \_\_\_\_\_\_\_soldering is the most widely used method of attaching surface mount components to printed circuit boards (PCBs). | ii ) A\_\_\_\_\_\_\_\_  is a machine used primarily for [reflow soldering](https://en.wikipedia.org/wiki/Reflow_soldering) of [surface mount](https://en.wikipedia.org/wiki/Surface_mount) electronic components to [printed circuit boards](https://en.wikipedia.org/wiki/Printed_circuit_board) (PCB). | 1. Preheat is the\_\_\_\_\_ stage of the reflow process. |
| **Recall/ Remembering** | **Understanding** | **Understanding** |
| a) Wave | a) reflow oven | a) second |
| b) Reflow  Optical Light emitting display | b)wave oven | b) third   1. Optical Light emitting display |
| c) Pick and place | c) microwave oven | c) first |
| d) Machine | d) soldering oven | d) fourth |
| **Ans: (b)** | **Ans: (a)** | **Ans: (c)** |